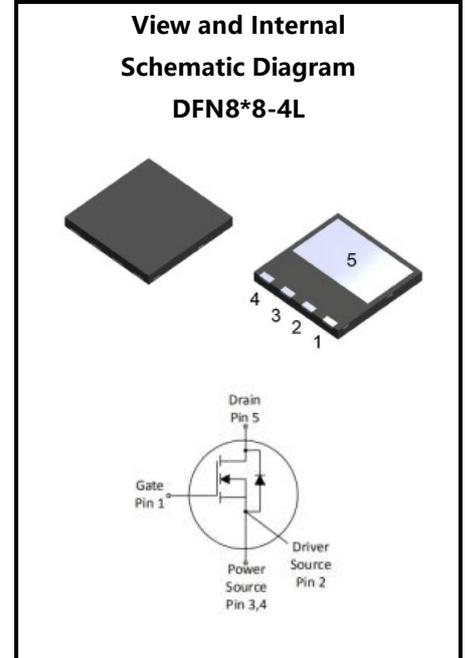


MOSFET

20A ,650V ,0.18Ω N-CHANNEL MOSFET

Features

- ◆ 20A,650V,RDS(ON)MAX=180mΩ@VGS=10V/5.5A
- ◆ Low gate charge
- ◆ Low Ciss
- ◆ Fast switching
- ◆ 100% avalanche tested
- ◆ Improved dv/dt capability
- ◆ RoHS 2.0 Compliant



Parameter	Values	Unit
BV_{dss}	650	V
I_D	20	A
$R_{Dson(max)}$	0.18	Ω
$V_{GS(th)}(typ)$	3	V

Ordering Code	Marking	Package	Packaging
X180N65JEFHW4	X180N65JEFHW4	DFN8*8-4L	Tape and Reel

Absolute Maximum Ratings($T_C=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Drain-Source Voltage	V_{DSS}	-	-	650	V	-
Gate-Source Voltage	V_{GS}	-20	-	20	V	-
Continuous Drain Current	I_D	-	-	20	A	$T_C=25^{\circ}C$
Pulsed Drain Current (Note 1)	I_{DM}	-	-	60	A	
Single Pulse Avalanche Energy (Note 2)	E_{AS}	-	-	80	mJ	
Maximum Power Dissipation	P_D	-	-	30	W	$T_C=25^{\circ}C$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55	-	150	$^{\circ}C$	-
Maximum lead temperature for soldering purposes, 1/8" from case for 5	T_{sold}	-	-	260		

Thermal Characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Thermal resistance , Junction to Case	$R_{th(ch-c)}$	-	4.15	-	$^{\circ}C/W$	-

Electrical Characteristics (T_j=25°C, unless otherwise noted)

Static characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Drain-Source Breakdown Voltage	BV _{DSS}	650	-	-	V	V _{GS} =0V, I _D =250μA
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1	μA	V _{DS} =650V, V _{GS} =0V
Gate-Body Leakage Current, Forward	I _{GSSF}	-	-	100	nA	V _{GS} =20V, V _{DS} =0V
Gate-Body Leakage Current, Reverse	I _{GSSR}	-	-	-100	nA	V _{GS} =-20V, V _{DS} =0V
Gate-Source Threshold Voltage	V _{GS(th)}	2	-	4	V	V _{DS} =V _{GS} , I _D =250μA
Drain-Source On-State Resistance	R _{DS(on)}	-	0.145	0.18	Ω	V _{GS} =10V, I _D =5.5A

Dynamic characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Input Capacitance	C _{iss}	-	1661	-	pF	V _{DS} =25V, V _{GS} =0V, f=1.0MHZ
Output Capacitance	C _{oss}	-	113	-		
Reverse Transfer Capacitance	C _{rss}	-	46	-		
Turn-On Delay Time	t _{d(on)}	-	20	-	ns	V _{DD} =250V, R _G =9.1Ω, I _D =15A
Turn-On Rise Time	t _r	-	3	-		
Turn-Off Delay Time	t _{d(off)}	-	74	-		
Turn-Off Fall Time	t _f	-	9	-		

Gate charge characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Total Gate Charge	Q _g	-	25	-	nC	V _{DS} =400V, I _D =15A, V _{GS} =10V
Gate-Source Charge	Q _{gs}	-	8	-		
Gate-Drain Charge	Q _{gd}	-	7.5	-		

Reverse diode

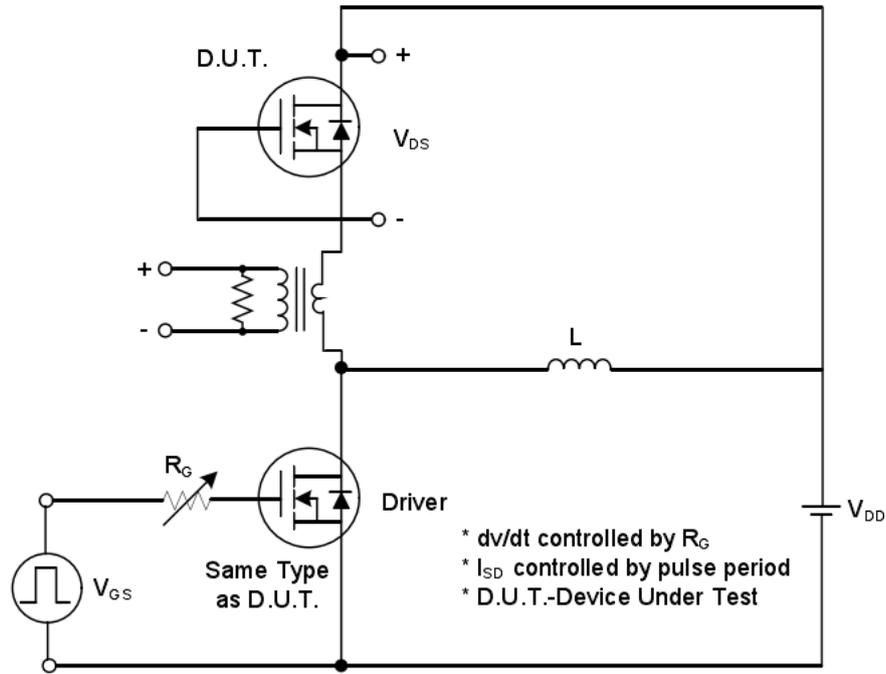
Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Continuous Diode Forward Current	I _S	-	-	20	A	-
Pulsed Diode Forward Current	I _{SM}	-	-	60	A	-
Diode Forward Voltage	V _{SD}	-	-	1.5	V	I _S =9A, V _{GS} =0V
Reverse Recovery Time	t _{rr}	-	400	-	ns	V _{GS} =0V, I _F =15A, di/dt=100A/μs
Reverse Recovery Charge	Q _{rr}	-	7.6	-	nC	(Note3)



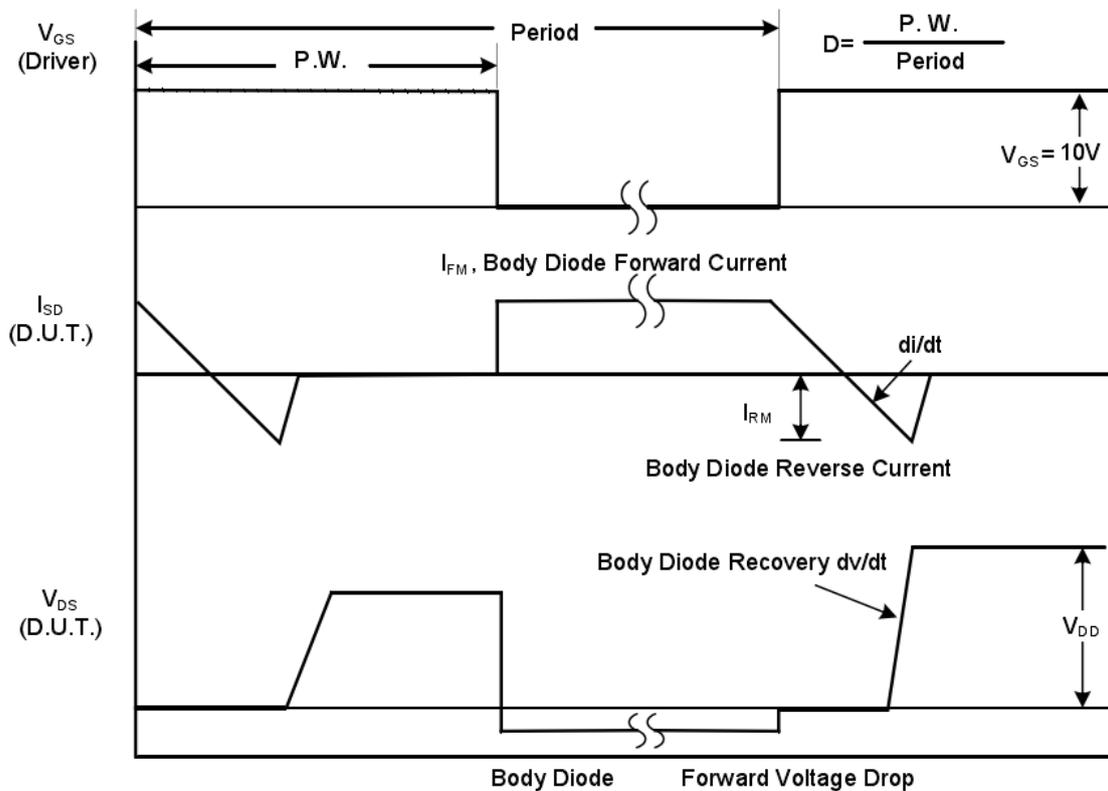
Notes

1. Repetitive Rating:pulse width limited by maximum junction temperature.
2. $L=10\text{mH}$, $R_g=25\Omega$, $V_{DD}=50\text{V}$,starting $T_J=25^\circ\text{C}$.
3. Pulse width $\leq 300\mu\text{s}$;duty cycle $\leq 2\%$.

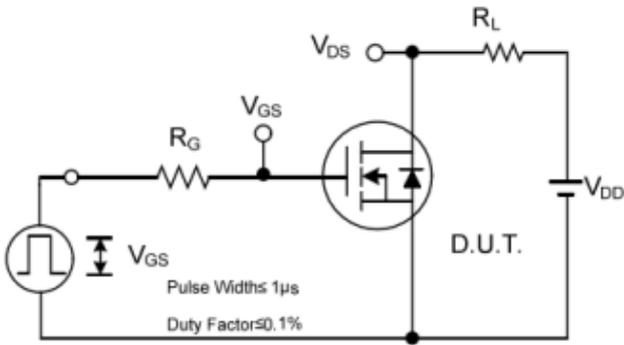
RATING AND CHARACTERISTIC CURVES



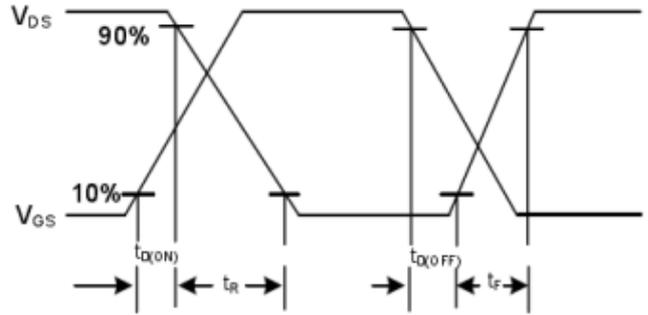
Peak Diode Recovery dv/dt Test Circuit



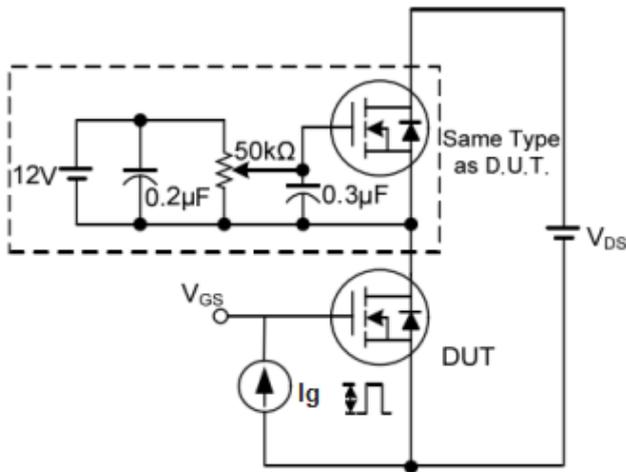
Peak Diode Recovery dv/dt Waveforms



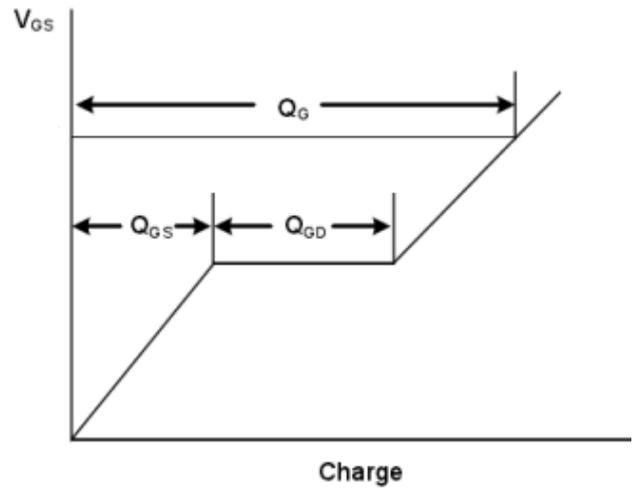
Switching Test Circuit



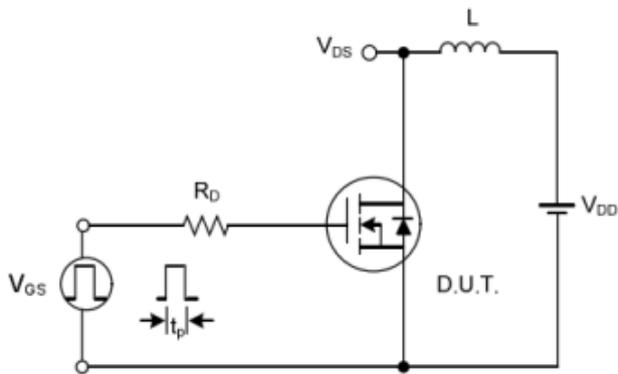
Switching Waveforms



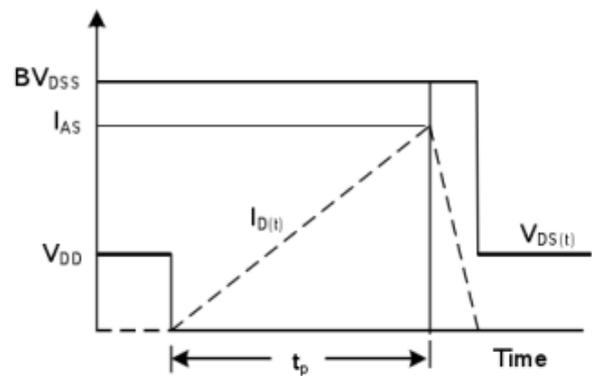
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

RATING AND CHARACTERISTIC CURVES

Figure.1 Typical Output Characteristics

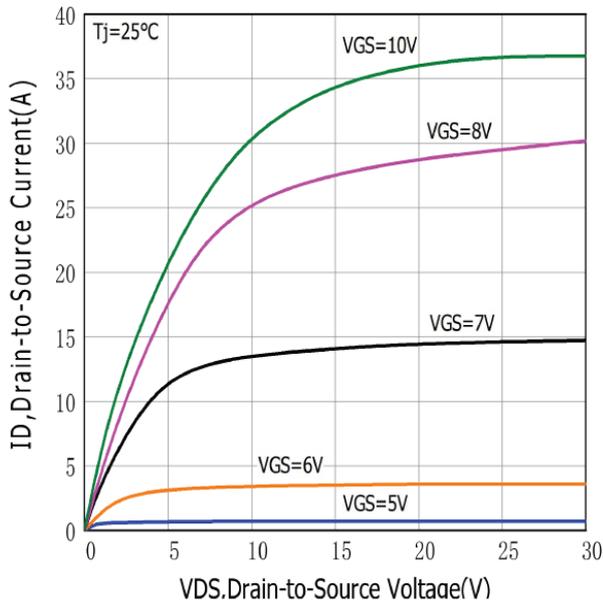


Figure.2 Typical Gate Charge vs Gate to Source Voltage

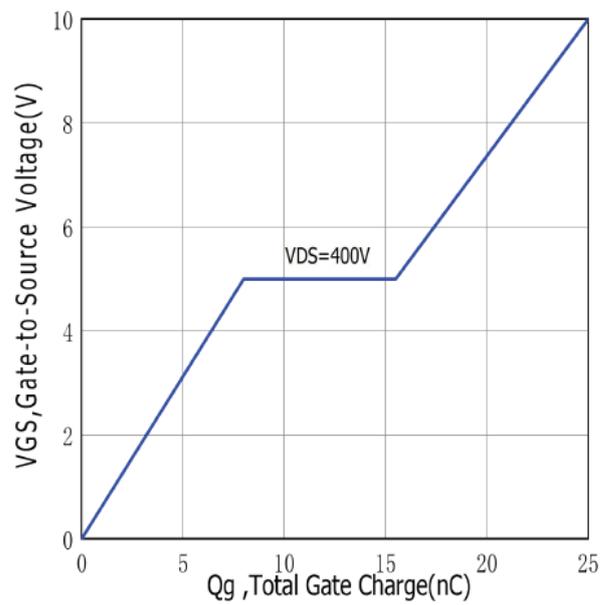


Figure.3 Typical Body Diode Transfer Characteristics

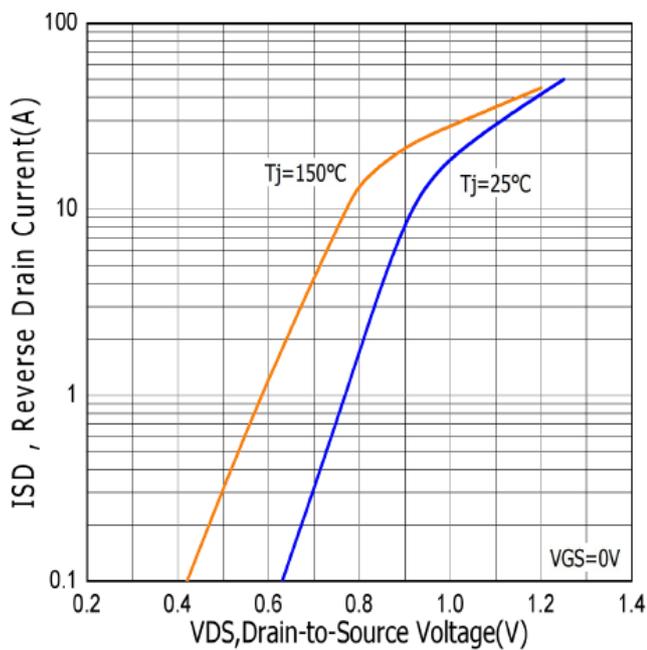


Figure.4 Typical Capacitance vs Drain to Source Voltage

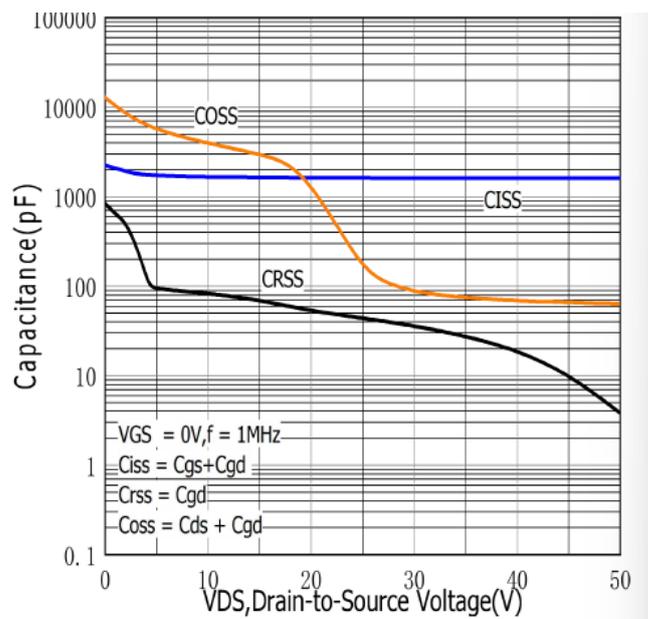


Figure.5 Typical Breakdown Voltage vs Junction Temperature

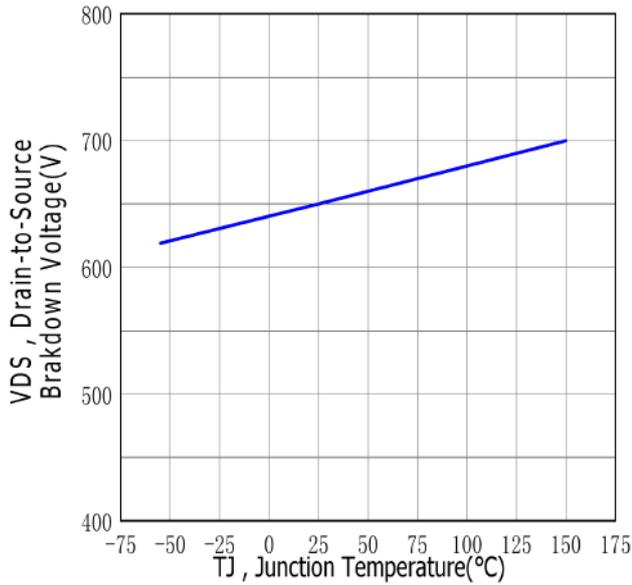


Figure.6 Typical Drain to Source on Resistance vs Junction Temperature

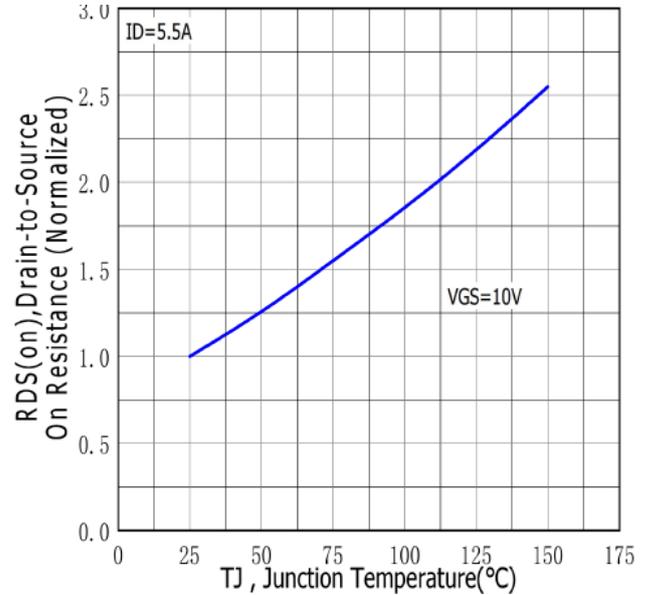


Figure.7 Maximum Forward Bias Safe Operating Area

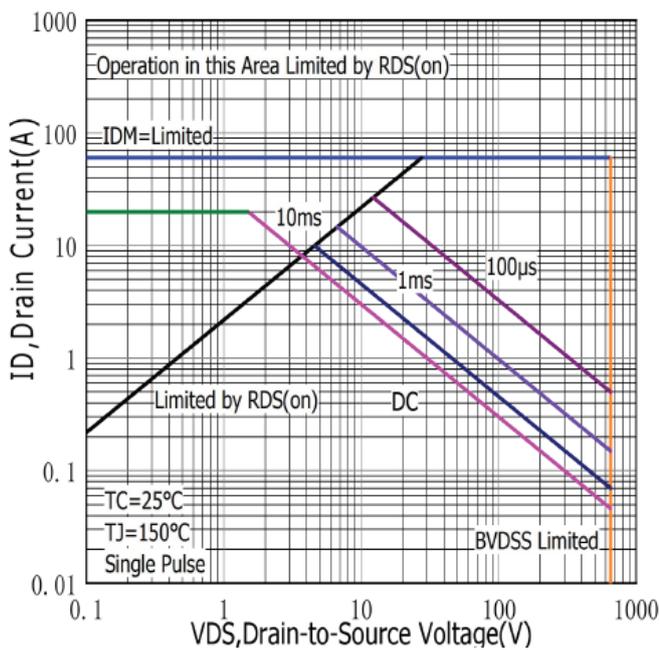


Figure.8 Typical Drain to Source ON Resistance vs Drain Current

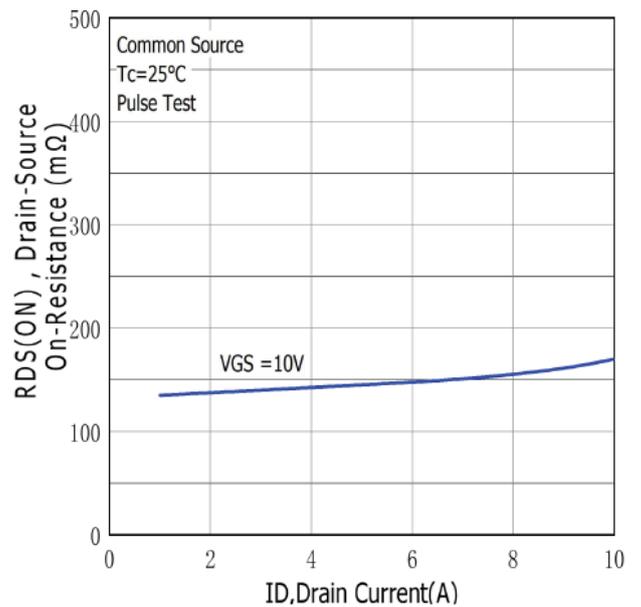


Figure.9 Maximum EAS vs Channel Temperature

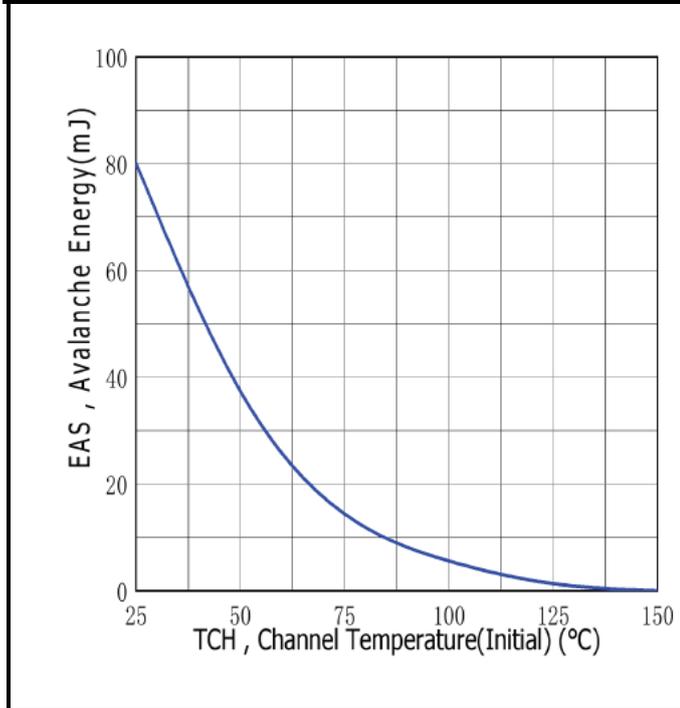


Figure.10 Typical Threshold Voltage vs Case Temperature

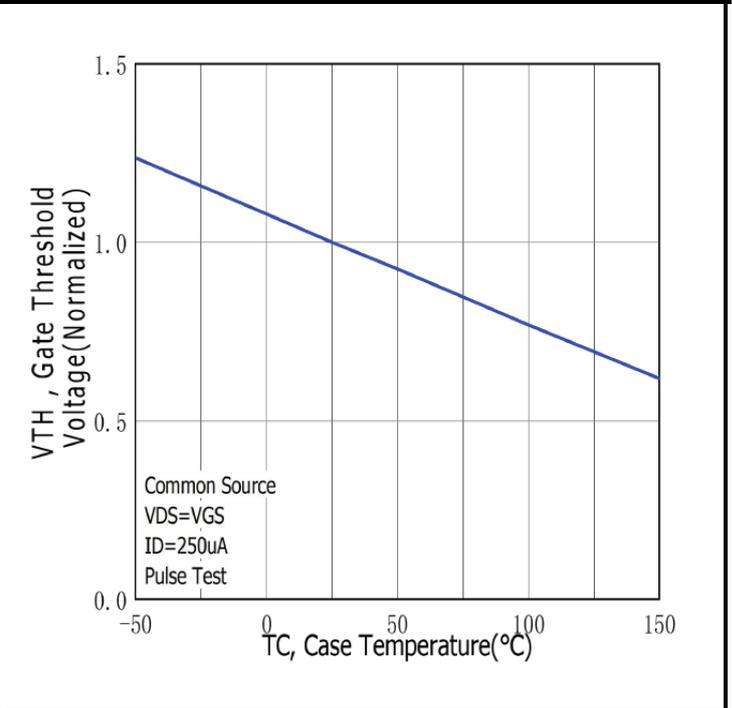


Figure.11 Typical Transfer Characteristics

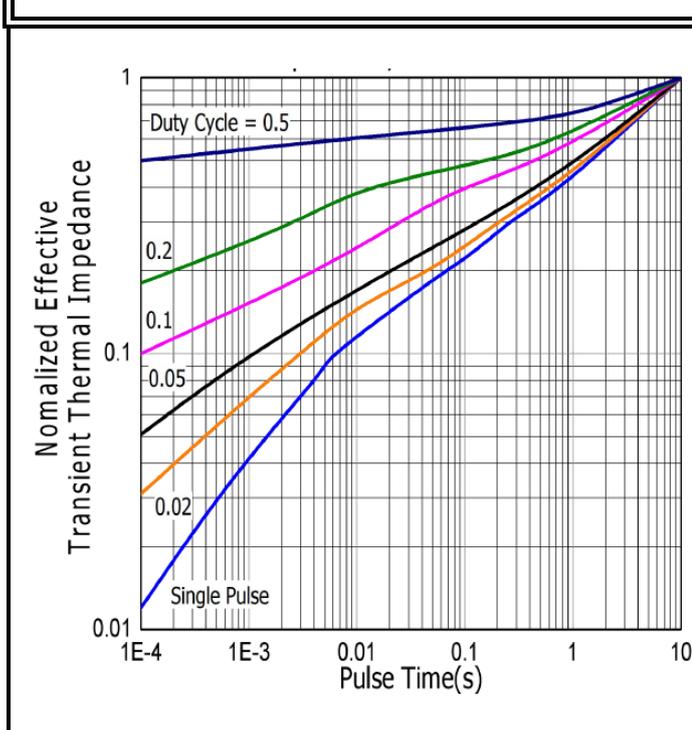
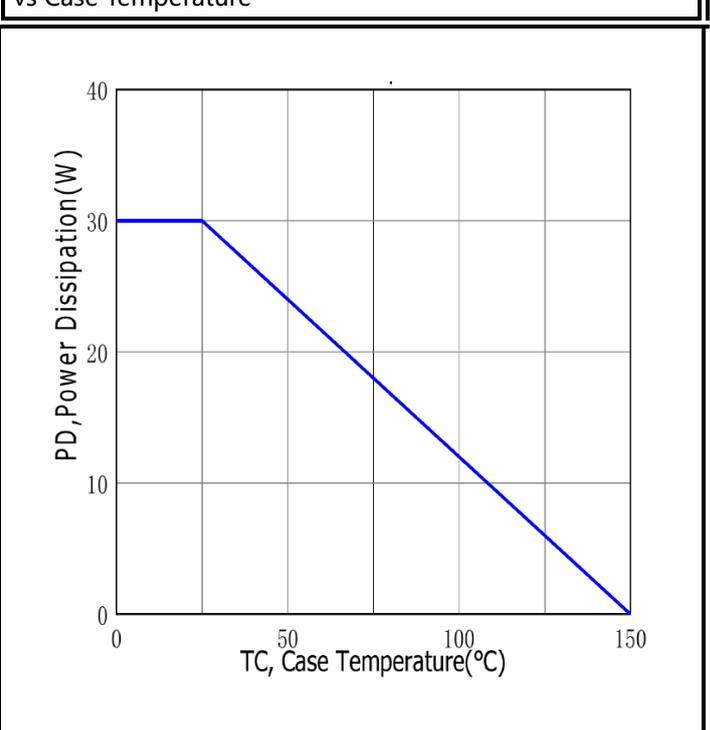
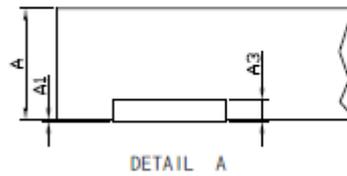
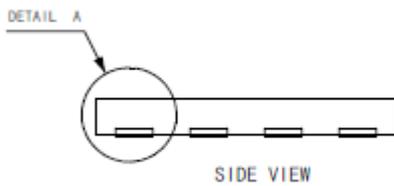
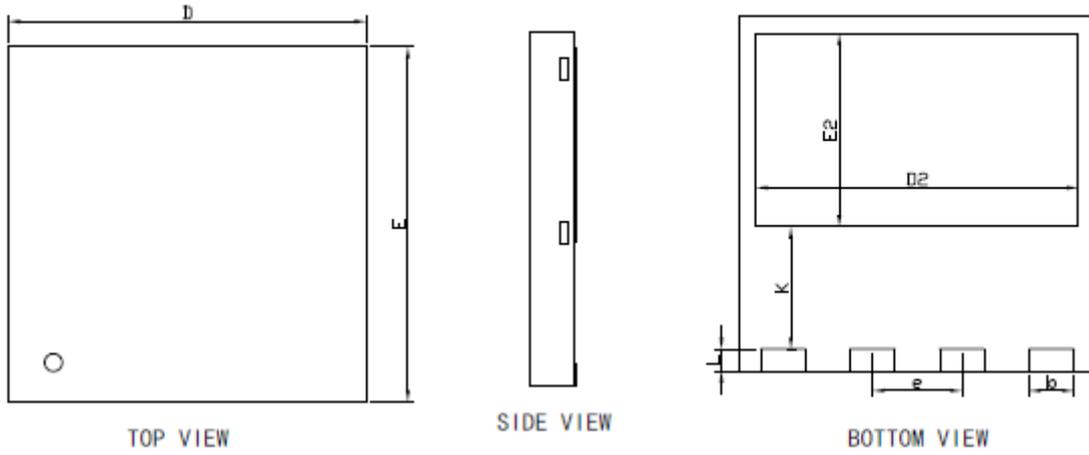


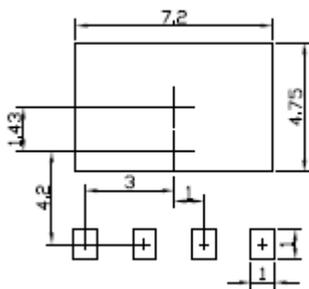
Figure.12 Maximum Power Dissipation vs Case Temperature



Outline Package: DFN8*8-4L



RECOMMENDED LAND PATTERN



UNIT: mm

	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	0.02	0.05
A3		0.20	
b	0.90	1.00	1.10
D	7.90	8.00	8.10
E	7.90	8.00	8.10
D2	7.10	7.20	7.30
E2	4.25	4.35	4.45
e	1.90	2.00	2.10
K	2.65	2.75	2.85
L	0.40	0.50	0.60